




<b>SMC</b>		<b>Features</b>					
		<ul style="list-style-type: none"> <li>• Low forward voltage drop</li> <li>• High current capability</li> <li>• Moisture sensitivity: level 1, per J-STD-020</li> <li>• AEC-Q101 qualified</li> <li>• High temperature soldering guaranteed: 260°C/10 seconds</li> <li>• Halogen-free according to IEC 61249-2-21 definition</li> </ul>					
<b>Primary characteristics</b>		<b>Applications</b>					
$I_{F(AV)}$	3A	For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications					
$V_{RRM}$	20V to 60V	<b>Mechanical data</b>					
$I_{FSM}$	100A						
$I_{RM}$	0.2/0.15mA						
$V_{FM}$ at $I_F=3A$	0.55/0.7V						
$T_J$ max.	150 °C						
<b>Maximum rating (Ta=25°C unless otherwise noted)</b>							
Parameter	Sym	SMC					Unit
		SS32	SS33	SS34	SS35	SS36	
Max. repetitive peak reverse voltage	$V_{RRM}$	20	30	40	50	60	V
Max. RMS reverse voltage	$V_{RMS}$	14	21	28	35	42	V
Max. DC blocking voltage	$V_{DC}$	20	30	40	50	60	V
Max. average forward current	$I_{F(AV)}$	3					A
Non-repetitive peak forward surge current 8.3ms single half-sine-wave	$I_{FSM}$	100					A
Max. instantaneous forward voltage drop per diode	$V_{FM}$	0.55			0.7		V
Max. instantaneous reverse current at rated DC blocking voltage	$I_{RM}$	Ta=25 °C		0.2			mA
		Ta=125 °C		10			
Operating junction temperature	$T_J$	-55 ~ +150					°C
Storage temperature	$T_{STG}$	-55 ~ +150					°C
Typical thermal resistance (Note1)	$R_{\theta J-L}$	15					°C/W
	$R_{\theta J-A}$	65					
	$R_{\theta J-C}$	25					

**Notes:**

1 The thermal resistance from junction to lead, ambient and cover.



**Ordering information (Example)**

PREFERRED	UNITWEIGHT(g)	PREFERREDPACKAGECODE	BASEQUANTITY	DELIVERYMODE
SS32				

**Typical characteristics**

(TA = 25°C unless otherwise noted)

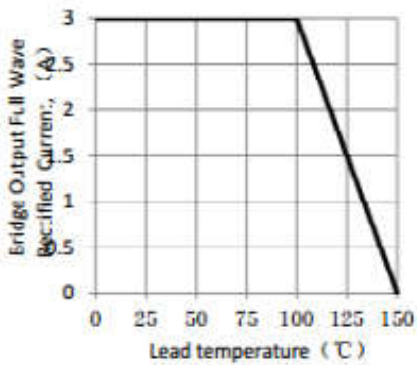


Figure 1. Forward Current Derating Curve

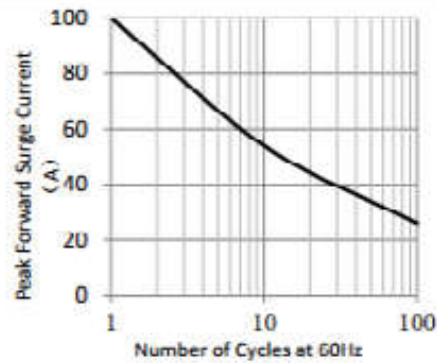


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

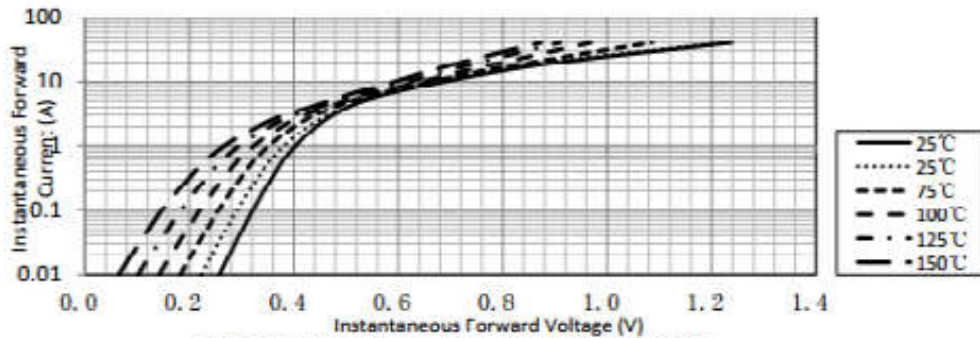


Figure 3. Typical Instantaneous Forward Characteristics

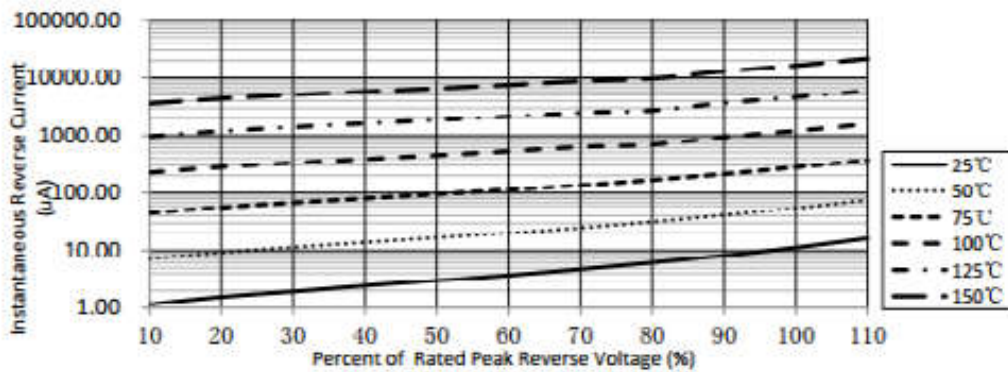


Figure 4. Typical Reverse Characteristics



Typical characteristics

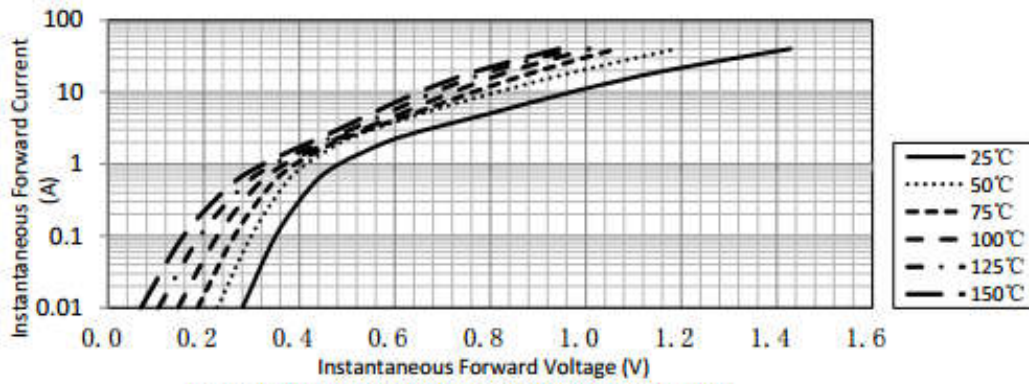


Figure 5. Typical Instantaneous Forward Characteristics

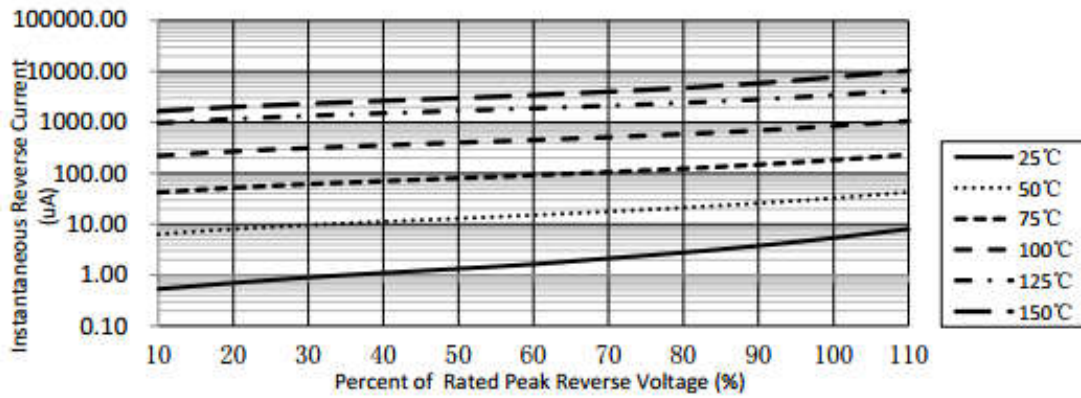
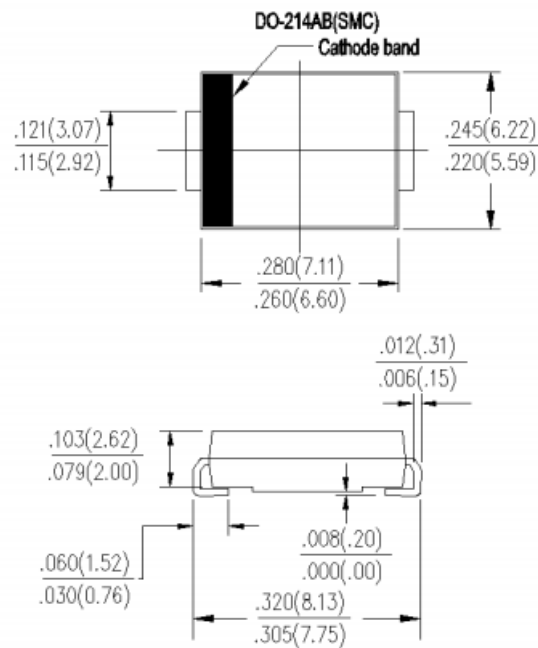


Figure 6. Typical Reverse Characteristics



Package outline dimensions



Gold SEMI Inc. - Legal Notice

Disclaimer – All data and specifications are subject to changes without notice

GOLD SEMI Inc, it's affiliates, agents, distributors and employees neither accept nor assume any responsibility for errors or inaccuracies. All data and specifications are intended for information and provide a product description only. Electrical and mechanical parameters listed in GOLD SEMI data sheets and specifications will vary dependent upon application and environmental conditions .GOLD SEMI is not liable for any damages occurred or resulting from any circuit, product or end-use application for which it's products are used. GOLD SEMI products are not intended or designed for use in life saving or sustaining apparatus and purchase of any GOLD SEMI products automatically indemnifies GOLD SEMI against any claims or damages resulting from application malfunction